



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

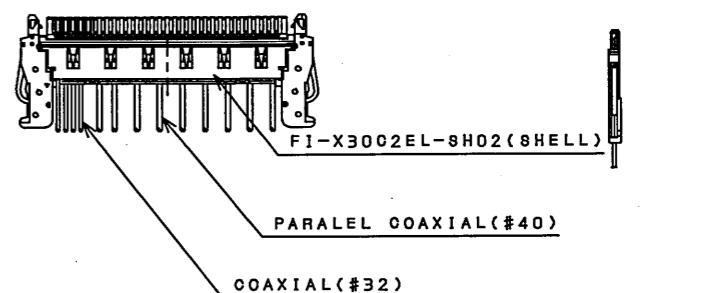
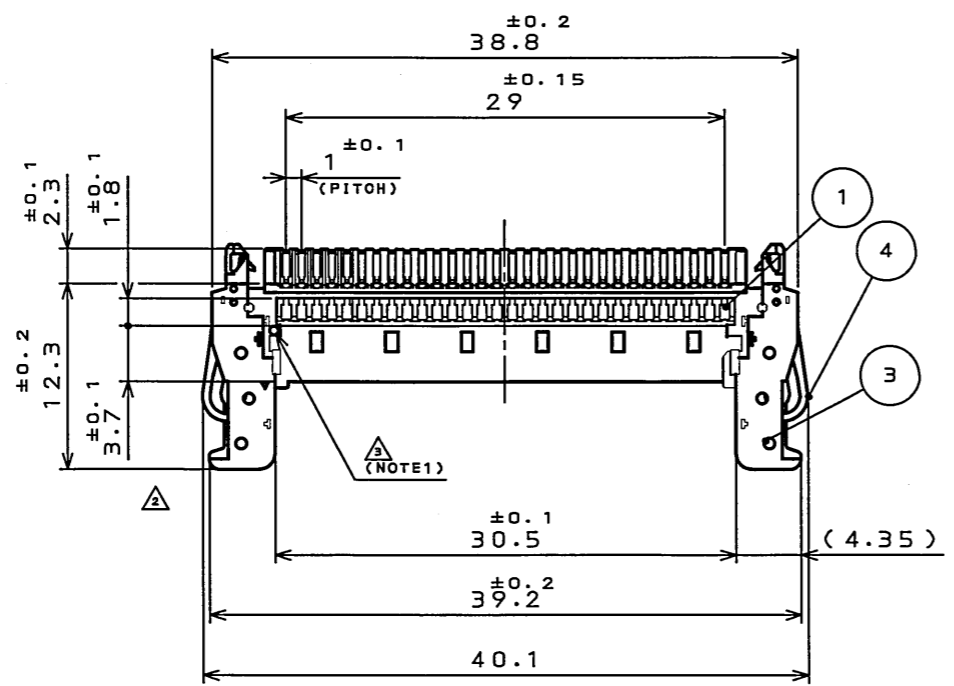
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

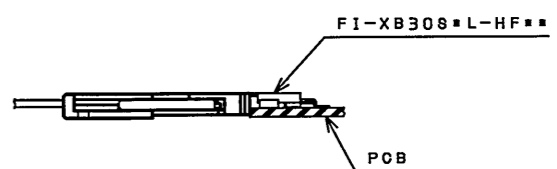
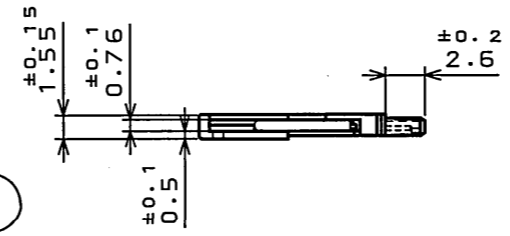


SJ100714
図面番号(DRAWING NO.)

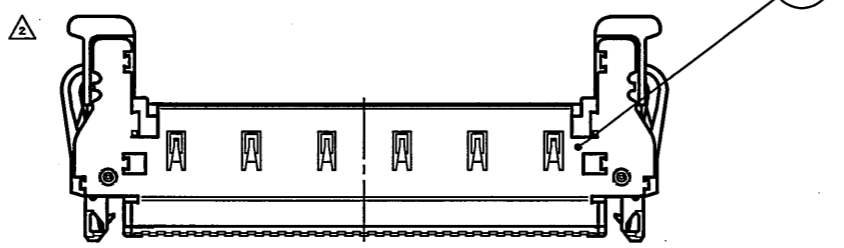
版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	5.Jan.2005	056509	REVISED FORM 形状変更		K.HISAMATSU	M.SUZUKI	K.HISATOMI
3	16.Aug.2006	060821	REVISED FORM 形状変更		T.SHIODA	M.Suzuki	K.Hisatomii



CABLE ASSEMBLED CONDITION(REF.)
ケーブル 嵌合状態図(参考)

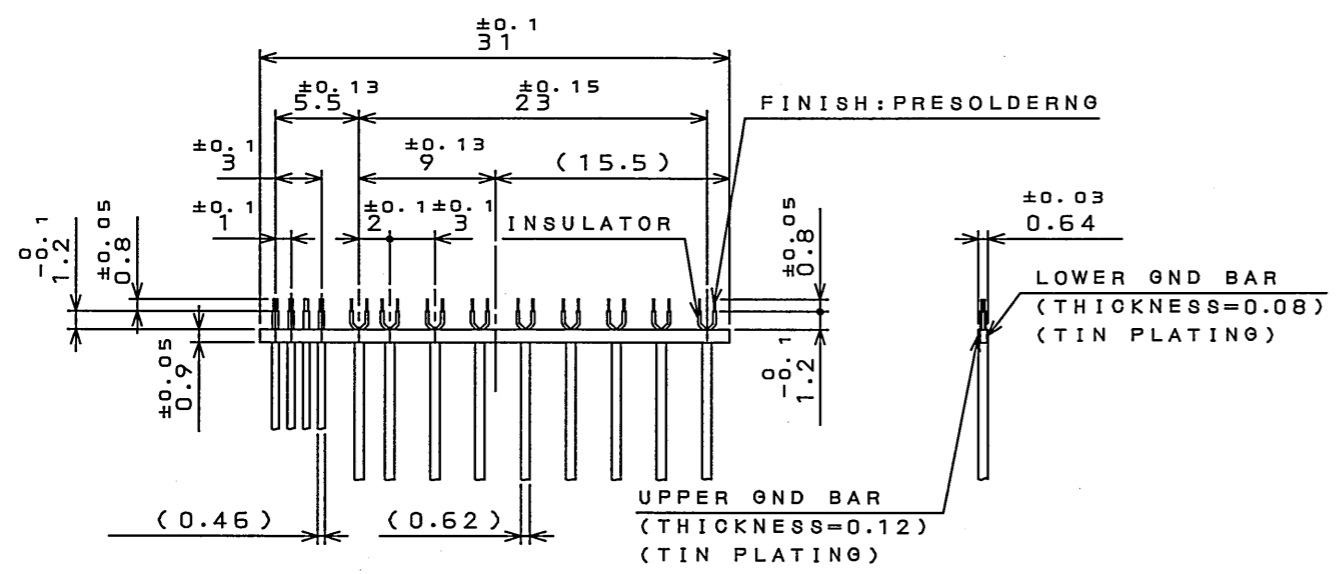


MATED CONDITION(REF.)
嵌合状態図(参考)



△ NOTE1. DENT FOR IDENTIFICATION TO THE POSITION SHOWN IN FIGURE.

△ 注1. 図示の位置に識別の為のマーキング有り。



AFTER WIRE SOLDERING, CLEAN FLUX.

APPLICABLE WIRE DIMENSIONS(REF.)
適用ワイヤー加工寸法(参考)

符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
4	LOCK LEVER ロックレバー	2	STAINLESS STEEL ステンレス		
3	INSULATOR インシュレータ	1	HEAT RESISTING PLASTIC 耐熱性プラスチック		UL94 V-0 BLACK
2	GROUND PLATE グラウンドプレート	1	STAINLESS STEEL ステンレス	TIN PLATING Snメッキ	
1	CONTACT コンタクト	30	COPPER ALLOY 銅合金	GOLD(0.7μmMIN)OVER NICKEL Ni上Auメッキ(0.7μm以上)	SOLDERING AREA:TIN OVER NICKEL 半田付け部Ni上Snメッキ

仕様書(SPECIFICATION) JACS-1597- JAHL-1597-*		第1版(ORIGINAL DATE) 6.Apr.2004		尺度(SCALE) シリーズ(SERIES) 2:1 FI-X		日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.	
公差(GENERAL TOLERANCE)		製図 DR.		名称(TITLE)			
寸法(DIMENSION) 角度(ANGLES)		担当 CHK. K.HISAMATSU		FI-X3002EL (CABLE SIDE) (LEVER TYPE)			
. ±0.8 ° ±		査閲 APPD. M.SUZUKI					
.X ±0.4 °X ±		承認 APPD. Y.ICHIYAMA					
.XX ±0.1 °XX ±				質量(MASS)		図面番号(DRAWING NO.) 版数(REV.)	
.XXX ±						SJ100714 3	

LEAD FREE この製品は鉛フリー品です

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